

Title (en)  
LOCKING ELEMENT ATTACHING DEVICE

Title (de)  
GERÄT ZUM ANBRINGEN EINES BEFESTIGUNGSELEMENTS

Title (fr)  
DISPOSITIF DE POSE D'ATTACHES

Publication  
**EP 1366994 A4 20040519 (EN)**

Application  
**EP 02702721 A 20020301**

Priority  
• JP 0201935 W 20020301  
• JP 2001057204 A 20010301

Abstract (en)  
[origin: EP1366994A1] The present invention is to provide a tag attaching device which can enable one of the operator's hands other than his hand which is used for operating the tag attaching device to be used, to be free for separate necessary operation, when a predetermined tag should be attached to a predetermined good utilizing the tag attaching device 20 and thus it is disclosed that a tag attaching device 20 for attaching a tag attaching pin 1 comprising a filament section 4, an inserting head section 2 provided at one end of the filament section 4, and a socket section 15 or holding section 3 provided at the another end of the filament section 4, onto a predetermined good 100 with a tag 5 engaged on the filament section 4, by inserting the inserting head section 2 of the pin 1 into a hollow needle 21 provided on the tag attaching device 20 and penetrated through the good 100 and by pushing the inserting head 2 out of the hollow needle 21 utilizing a predetermined pin pushing means so as to have the inserting section 2 attached to a surface of the good 100 with the tag 5, wherein the device 20 being provided with a tag holding means 27 for tentatively holding the tag 5, 400 on the device 20, on a front end portion of the device 20 from a surface of which the hollow needle 21 being projected and at a position in the vicinity of the position from which the hollow needle 21 being projected. <IMAGE>

IPC 1-7  
**B65C 7/00**; G09F 3/00; G09F 3/16

IPC 8 full level  
**B65C 7/00** (2006.01)

CPC (source: EP US)  
**B65C 7/005** (2013.01 - EP US)

Citation (search report)  
• [X] US 6126056 A 20001003 - UENO HIDEYUKI [JP], et al  
• [A] US 5738265 A 19980414 - HIRAI TOMOYUKI [JP], et al  
• [A] US 3735908 A 19730529 - KINNEY J E, et al  
• [A] US 4526310 A 19850702 - LUNDEN BENGT [SE], et al  
• [A] DE 3625481 A1 19880211 - SCHIESSER AG [DE]  
• [A] US 4711369 A 19871208 - DUCHIN DANIEL [US]  
• [PX] PATENT ABSTRACTS OF JAPAN vol. 2000, no. 24 11 May 2001 (2001-05-11)  
• [X] PATENT ABSTRACTS OF JAPAN vol. 014, no. 209 (M - 0968) 27 April 1990 (1990-04-27)  
• See references of WO 02070351A1

Cited by  
CN102046475A

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DOCDB simple family (publication)  
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